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Team Nexperia

PEMH9; PIMH9; PUMH9

NPN/NPN resistor-equipped transistors;
R1 = 10 k Ω , R2 = 47 k Ω

Rev. 5 — 12 November 2013

Product data sheet

1. Product profile

1.1 General description

NPN/NPN double Resistor-Equipped Transistors (RET) in Surface-Mounted Device (SMD) plastic packages.

Table 1. Product overview

| Type number | Package | | PNP/PNP complement | NPN/PNP complement | Package configuration |
|-------------|---------|-------|--------------------|--------------------|---------------------------|
| | NXP | JEITA | | | |
| PEMH9 | SOT666 | - | PEMB9 | PEMD9 | ultra small and flat lead |
| PIMH9 | SOT457 | SC-74 | - | - | small |
| PUMH9 | SOT363 | SC-88 | PUMB9 | PUMD9 | very small |

1.2 Features and benefits

- 100 mA output current capability
- Built-in bias resistors
- Simplifies circuit design
- Reduces component count
- Reduces pick and place costs
- AEC-Q101 qualified

1.3 Applications

- Low current peripheral driver
- Control of IC inputs
- Replaces general-purpose transistors in digital applications

1.4 Quick reference data

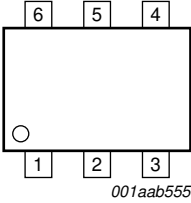
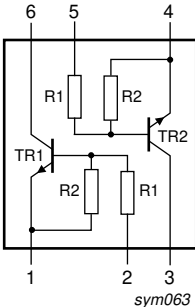
Table 2. Quick reference data

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-----------------------|---------------------------|------------|-----|-----|-----|------------|
| Per transistor | | | | | | |
| V _{CEO} | collector-emitter voltage | open base | - | - | 50 | V |
| I _O | output current | | - | - | 100 | mA |
| R1 | bias resistor 1 (input) | | 7 | 10 | 13 | k Ω |
| R2/R1 | bias resistor ratio | | 3.7 | 4.7 | 5.7 | |



2. Pinning information

Table 3. Pinning

| Pin | Description | Simplified outline | Graphic symbol |
|-----|------------------------|---|---|
| 1 | GND (emitter) TR1 |  |  |
| 2 | input (base) TR1 | | |
| 3 | output (collector) TR2 | | |
| 4 | GND (emitter) TR2 | | |
| 5 | input (base) TR2 | | |
| 6 | output (collector) TR1 | | |

3. Ordering information

Table 4. Ordering information

| Type number | Package | | Version |
|-------------|---------|--|---------|
| | Name | Description | |
| PEMH9 | - | plastic surface-mounted package; 6 leads | SOT666 |
| PIMH9 | SC-74 | plastic surface-mounted package (TSOP6); 6 leads | SOT457 |
| PUMH9 | SC-88 | plastic surface-mounted package; 6 leads | SOT363 |

4. Marking

Table 5. Marking codes

| Type number | Marking code ^[1] |
|-------------|-----------------------------|
| PEMH9 | H9 |
| PIMH9 | H9 |
| PUMH9 | H*9 |

[1] * = placeholder for manufacturing site code

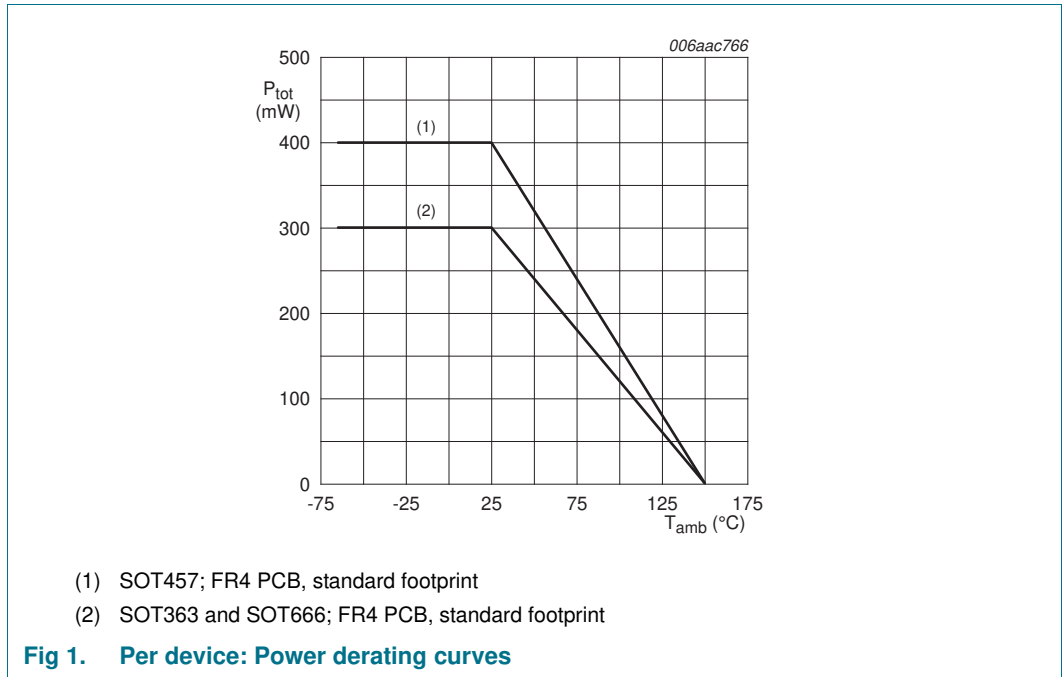
5. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit | | |
|-----------------------|---------------------------|--|----------------|------|------|-----|----|
| Per transistor | | | | | | | |
| V _{CBO} | collector-base voltage | open emitter | - | 50 | V | | |
| V _{CEO} | collector-emitter voltage | open base | - | 50 | V | | |
| V _{EBO} | emitter-base voltage | open collector | - | 6 | V | | |
| V _I | input voltage | positive | - | +40 | V | | |
| | | negative | - | -6 | V | | |
| | | | | | | | |
| I _O | output current | | - | 100 | mA | | |
| I _{CM} | peak collector current | single pulse; t _p ≤ 1 ms | - | 100 | mA | | |
| P _{tot} | total power dissipation | T _{amb} ≤ 25 °C | | | | | |
| | | | PEMH9 (SOT666) | [1] | - | 200 | mW |
| | | | PIMH9 (SOT457) | [1] | | 250 | mW |
| | | | PUMH9 (SOT363) | [1] | - | 200 | mW |
| Per device | | | | | | | |
| P _{tot} | total power dissipation | T _{amb} ≤ 25 °C | | | | | |
| | | | PEMH9 (SOT666) | [1] | - | 300 | mW |
| | | | PIMH9 (SOT457) | [1] | | 400 | mW |
| | | | PUMH9 (SOT363) | [1] | - | 300 | mW |
| T _j | junction temperature | | - | 150 | °C | | |
| T _{amb} | ambient temperature | | -55 | +150 | °C | | |
| T _{stg} | storage temperature | | -65 | +150 | °C | | |

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

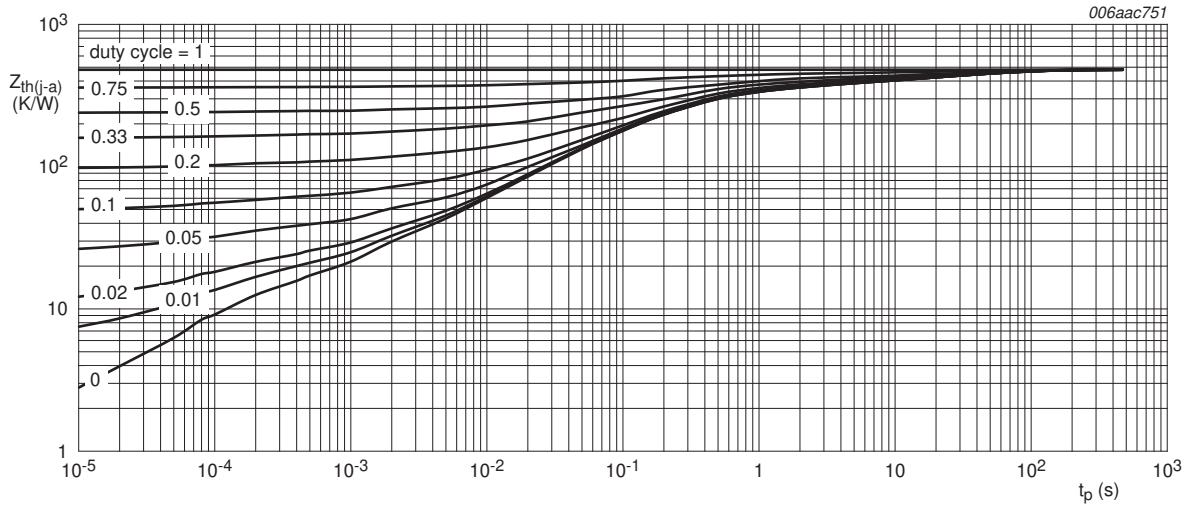


6. Thermal characteristics

Table 7. Thermal characteristics

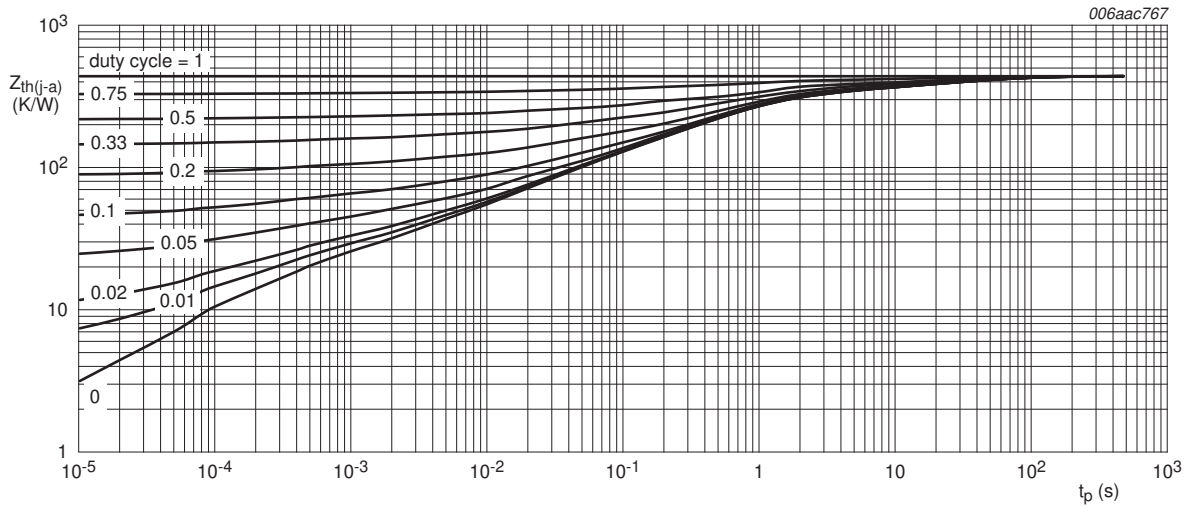
| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-----------------------|---|-------------|-----|-----|-----|------|
| Per transistor | | | | | | |
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | in free air | | | | |
| | PEMH9 (SOT666) | | [1] | - | 625 | K/W |
| | PIMH9 (SOT457) | | [1] | - | 500 | K/W |
| | PUMH9 (SOT363) | | [1] | - | 625 | K/W |
| Per device | | | | | | |
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | in free air | | | | |
| | PEMH9 (SOT666) | | [1] | - | 417 | K/W |
| | PIMH9 (SOT457) | | [1] | - | 313 | K/W |
| | PUMH9 (SOT363) | | [1] | - | 417 | K/W |

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.



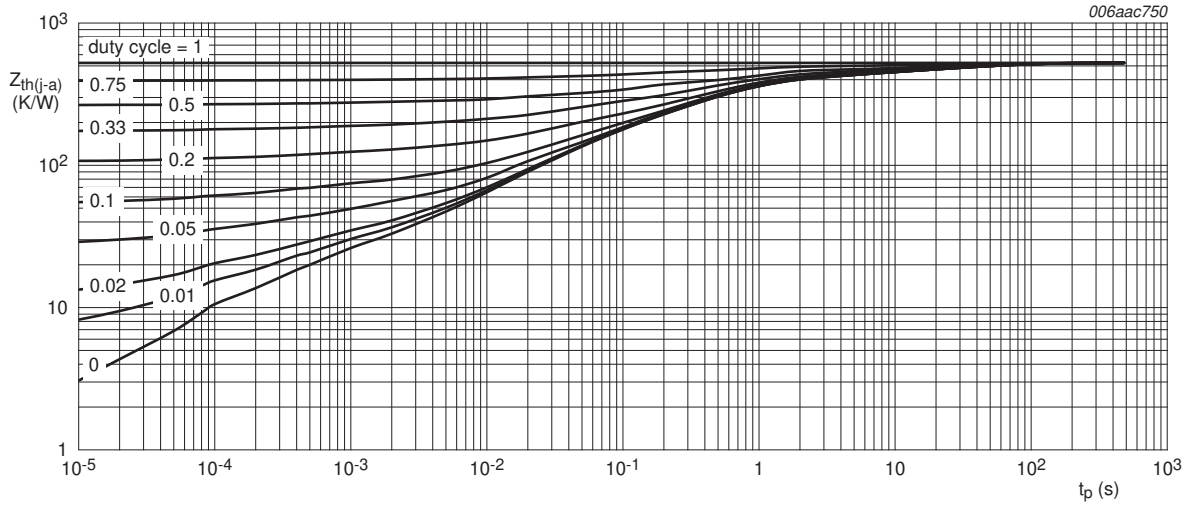
FR4 PCB, standard footprint

Fig 2. Per transistor: Transient thermal impedance from junction to ambient as a function of pulse duration for PEMH9 (SOT666); typical values



FR4 PCB, standard footprint

Fig 3. Per transistor: Transient thermal impedance from junction to ambient as a function of pulse duration for PIMH9 (SOT457); typical values



FR4 PCB, standard footprint

Fig 4. Per transistor: Transient thermal impedance from junction to ambient as a function of pulse duration for PUMH9 (SOT363); typical values

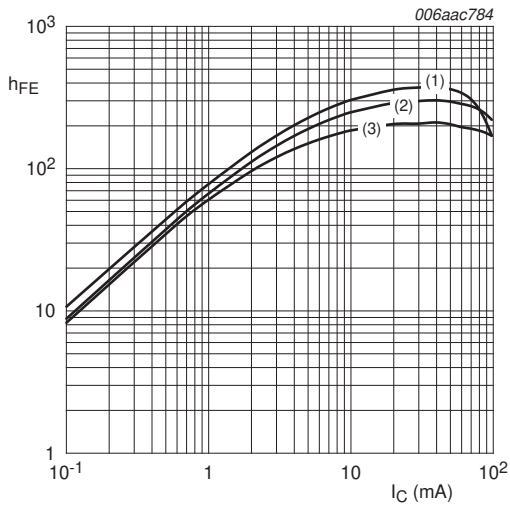
7. Characteristics

Table 8. Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

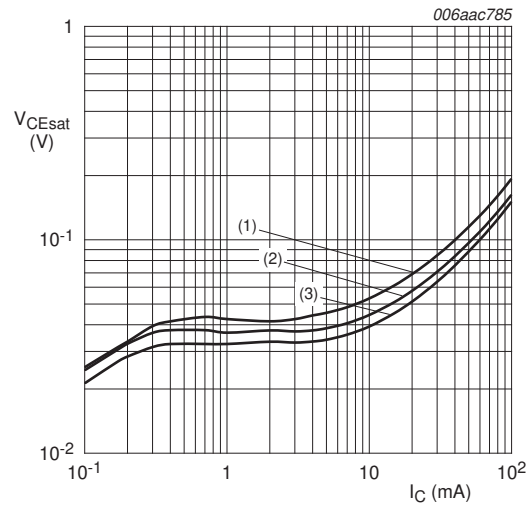
| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-----------------------|--------------------------------------|---|-----|-----|-----|---------------|
| Per transistor | | | | | | |
| I_{CBO} | collector-base cut-off current | $V_{CB} = 50\text{ V}; I_E = 0\text{ A}$ | - | - | 100 | nA |
| I_{CEO} | collector-emitter cut-off current | $V_{CE} = 30\text{ V}; I_B = 0\text{ A}$ | - | - | 100 | nA |
| | | $V_{CE} = 30\text{ V}; I_B = 0\text{ A}; T_j = 150\text{ }^{\circ}\text{C}$ | - | - | 5 | μA |
| I_{EBO} | emitter-base cut-off current | $V_{EB} = 5\text{ V}; I_C = 0\text{ A}$ | - | - | 150 | μA |
| h_{FE} | DC current gain | $V_{CE} = 5\text{ V}; I_C = 5\text{ mA}$ | 100 | - | - | |
| V_{CEsat} | collector-emitter saturation voltage | $I_C = 5\text{ mA}; I_B = 0.25\text{ mA}$ | - | - | 100 | mV |
| $V_{I(off)}$ | off-state input voltage | $V_{CE} = 5\text{ V}; I_C = 100\text{ }\mu\text{A}$ | - | 0.7 | 0.5 | V |
| $V_{I(on)}$ | on-state input voltage | $V_{CE} = 0.3\text{ V}; I_C = 1\text{ mA}$ | 1.4 | 0.8 | - | V |
| R1 | bias resistor 1 (input) | | 7 | 10 | 13 | k Ω |
| R2/R1 | bias resistor ratio | | 3.7 | 4.7 | 5.7 | |
| C_c | collector capacitance | $V_{CB} = 10\text{ V}; I_E = i_e = 0\text{ A}; f = 1\text{ MHz}$ | - | - | 2.5 | pF |
| f_T | transition frequency | $V_{CE} = 5\text{ V}; I_C = 10\text{ mA}; f = 100\text{ MHz}$ | [1] | 230 | - | MHz |

[1] Characteristics of built-in transistor



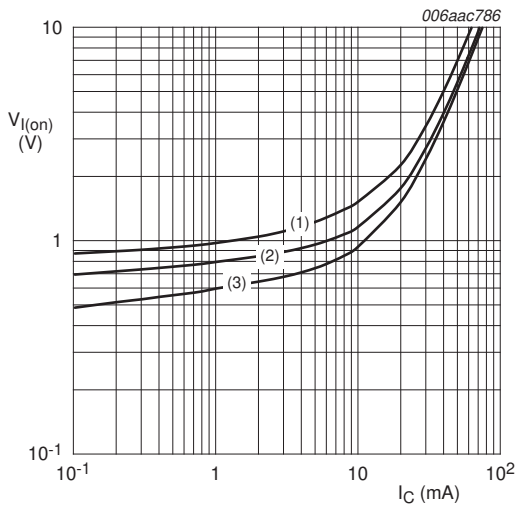
$V_{CE} = 5\text{ V}$
 (1) $T_{amb} = 100\text{ }^{\circ}\text{C}$
 (2) $T_{amb} = 25\text{ }^{\circ}\text{C}$
 (3) $T_{amb} = -40\text{ }^{\circ}\text{C}$

Fig 5. DC current gain as a function of collector current; typical values



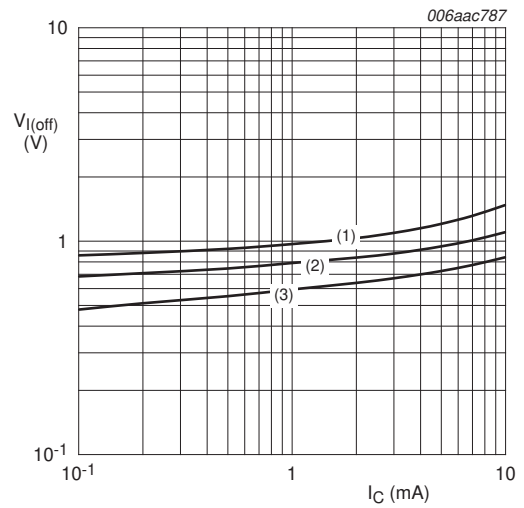
$I_C/I_B = 20$
 (1) $T_{amb} = 100\text{ }^{\circ}\text{C}$
 (2) $T_{amb} = 25\text{ }^{\circ}\text{C}$
 (3) $T_{amb} = -40\text{ }^{\circ}\text{C}$

Fig 6. Collector-emitter saturation voltage as a function of collector current; typical values



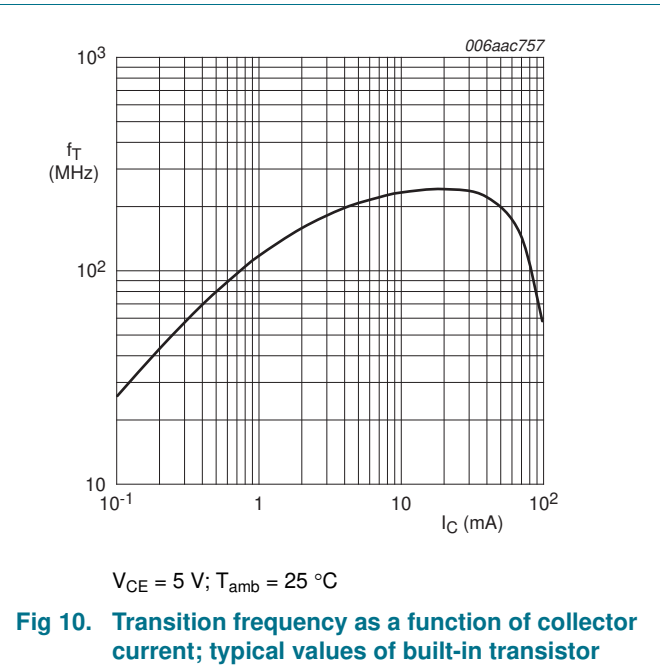
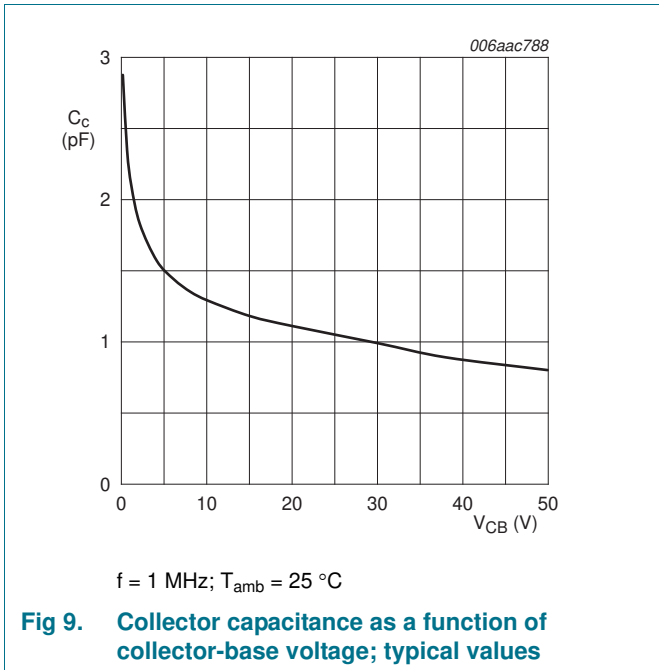
$V_{CE} = 0.3\text{ V}$
 (1) $T_{amb} = -40\text{ }^{\circ}\text{C}$
 (2) $T_{amb} = 25\text{ }^{\circ}\text{C}$
 (3) $T_{amb} = 100\text{ }^{\circ}\text{C}$

Fig 7. On-state input voltage as a function of collector current; typical values



$V_{CE} = 5\text{ V}$
 (1) $T_{amb} = -40\text{ }^{\circ}\text{C}$
 (2) $T_{amb} = 25\text{ }^{\circ}\text{C}$
 (3) $T_{amb} = 100\text{ }^{\circ}\text{C}$

Fig 8. Off-state input voltage as a function of collector current; typical values

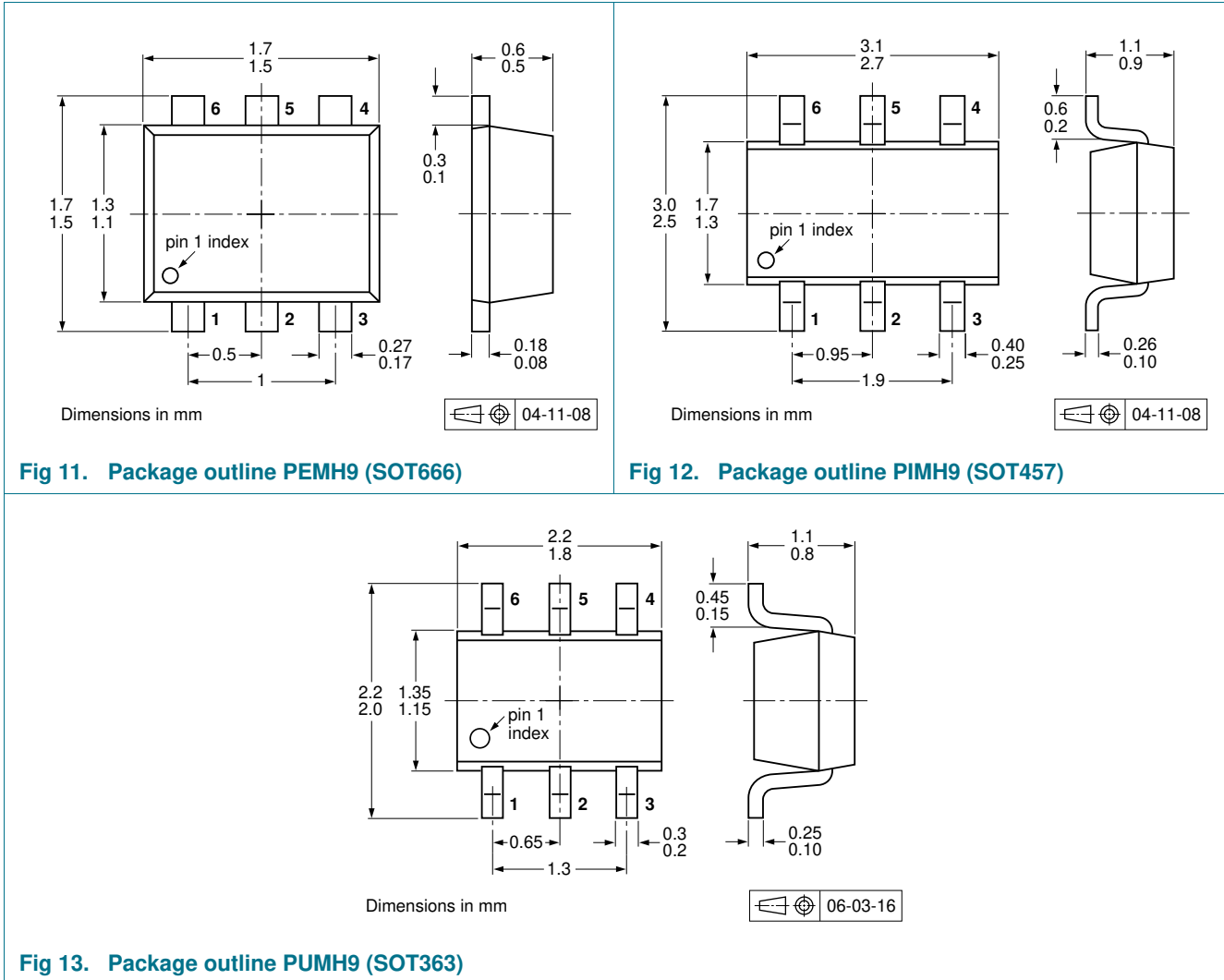


8. Test information

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

9. Package outline



10. Soldering

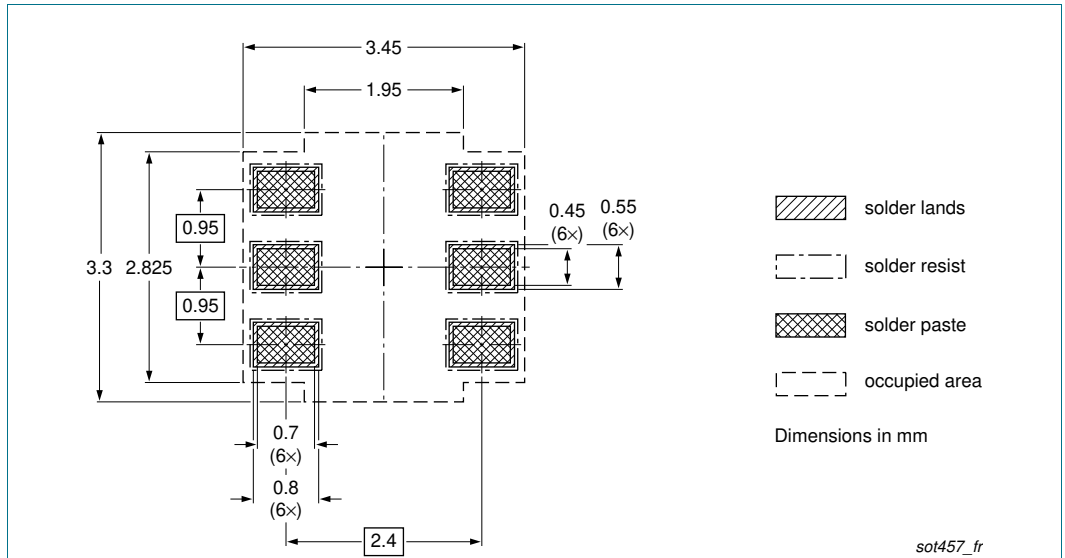


Fig 14. Reflow soldering footprint PIMH9 (SOT457)

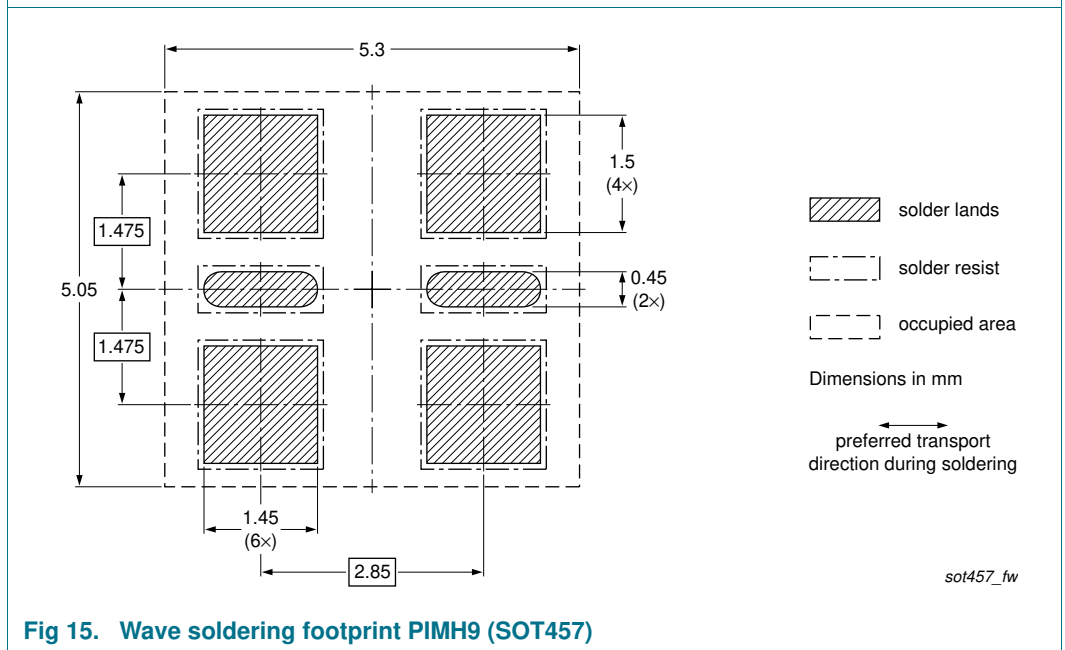


Fig 15. Wave soldering footprint PIMH9 (SOT457)

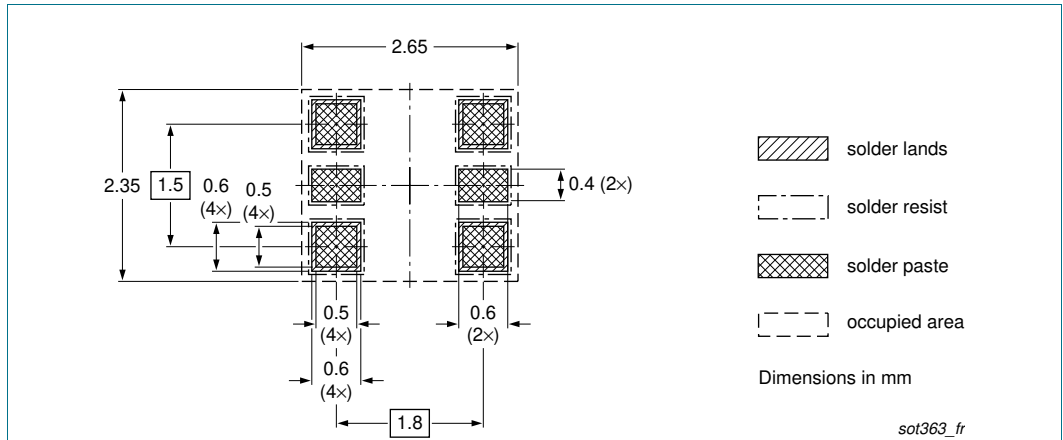


Fig 16. Reflow soldering footprint PUMH9 (SOT363)

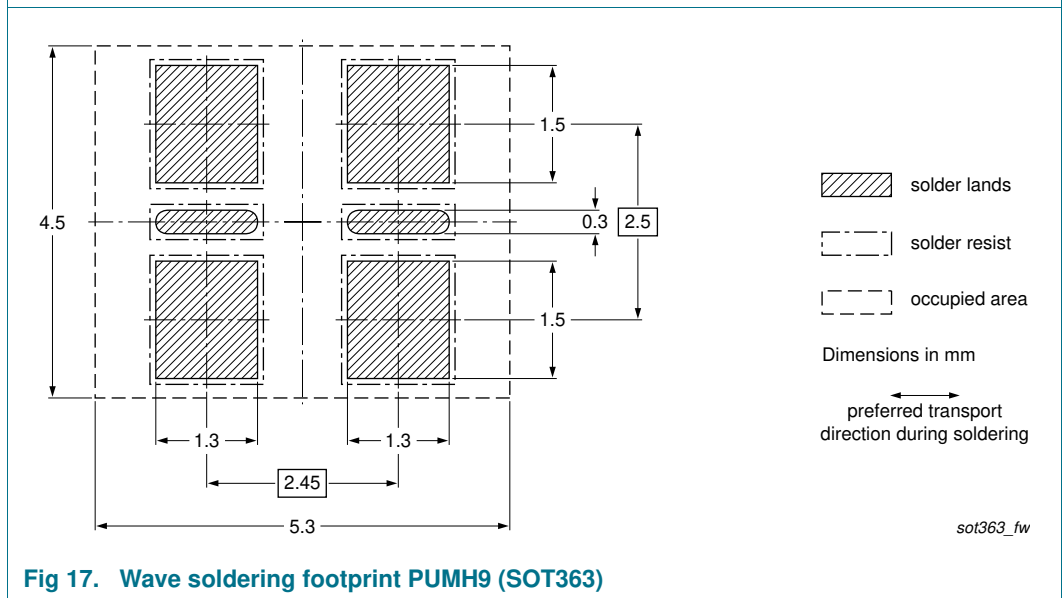
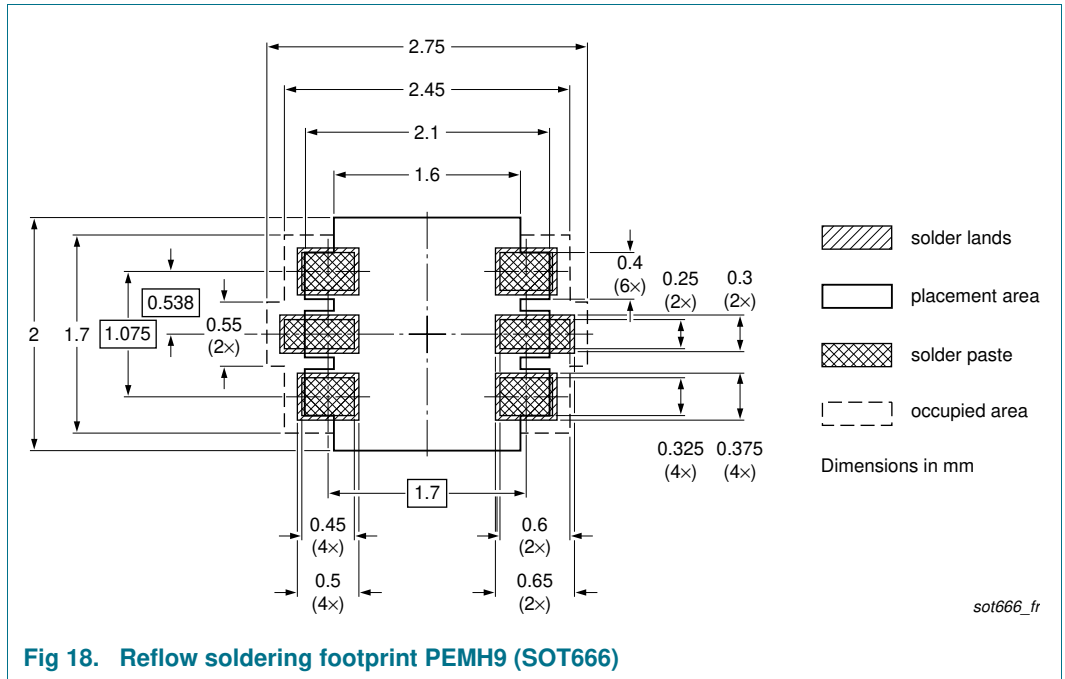


Fig 17. Wave soldering footprint PUMH9 (SOT363)



11. Revision history

Table 9. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|-----------------------|--|-----------------------|---------------|-----------------------|
| PEMH9_PIMH9_PUMH9 v.5 | 20131112 | Product data sheet | - | PIMH9_PUMH9_PEMH9 v.4 |
| Modifications: | <ul style="list-style-type: none"> • The format of this document has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Section 1 “Product profile”: updated • Section 4 “Marking”: updated • Figure 1 to 10: added • Section 5 “Limiting values”: updated • Section 6 “Thermal characteristics”: updated • Table 8 “Characteristics”: $V_{i(on)}$ redefined to $V_{i(on)}$ on-state input voltage, $V_{i(off)}$ redefined to $V_{i(off)}$ off-state input voltage, I_{CEO} updated, f_T added • Section 8 “Test information”: added • Section 9 “Package outline”: superseded by minimized package outline drawings • Section 10 “Soldering”: added • Section 12 “Legal information”: updated | | | |
| PIMH9_PUMH9_PEMH9 v.4 | 20040414 | Product data sheet | - | PIMH9_PUMH9_PEMH9 v.3 |
| PIMH9_PUMH9_PEMH9 v.3 | 20030915 | Product specification | - | - |

12. Legal information

12.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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